





DUAL NPN SMALL SIGNAL SURFACE MOUNT TRANSISTOR

Features

- Epitaxial Planar Die Construction
- Ideally Suited for Automated Assembly Processes
- Lead, Halogen and Antimony Free, RoHS Compliant (Note 1)
- "Green" Device (Note 2)
- Ultra Small Package

Mechanical Data

- Case: SOT-963
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Copper leadframe.
 Solderable per MIL-STD-202, Method 208
- Weight: 0.0027 grams (approximate)

SOT-963



Top View



Device Schematic

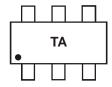
Ordering Information

Device	Packaging	Shipping
DST847BD.I-7	SOT-963	10 000/Tape & Reel

Notes:

- 1. No purposefully added lead. Halogen and Antimony Free.
- 2. Diodes Inc's "Green" Policy can be found on our website at http://www.diodes.com

Marking Information



TA = Product Type Marking Code



Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	50	V
Collector-Emitter Voltage	V_{CEO}	45	V
Emitter-Base Voltage	V _{EBO}	6.0	V
Collector Current - Continuous (Note 3)	Ic	100	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 3)	P _D	300	mW
Thermal Resistance, Junction to Ambient (Note 3)	$R_{ heta JA}$	417	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Notes: 3. Device mounted on FR-4 PCB with minimum recommended pad layout.

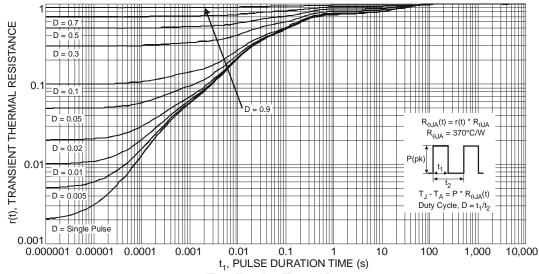


Fig. 1 Transient Thermal Response

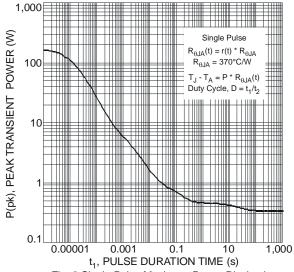


Fig. 2 Single Pulse Maximum Power Dissipation

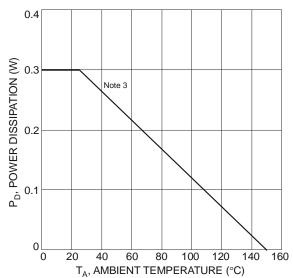


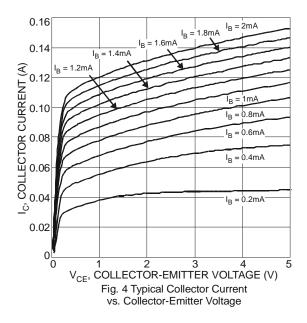
Fig. 3 Power Dissipation vs. Ambient Temperature



Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic (Note 4)	Symbol	Min	Typical	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	V _{(BR)CBO}	50	150		V	$I_C = 10\mu A, I_B = 0$
Collector-Emitter Breakdown Voltage	V _{(BR)CES}	50	150		V	$I_C = 10\mu A, I_B = 0$
Collector-Emitter Breakdown Voltage	V _{(BR)CEO}	45	65		V	$I_C = 1 \text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	6	8.35		V	$I_E = 1\mu A, I_C = 0$
Collector-Base Cutoff Current	I _{CBO}			15	nA	V _{CB} = 30V
DC Current Gain	h _{FE}	100 200	220 300	470		$I_C = 10\mu A, V_{CE} = 5V$ $I_C = 2.0mA, V_{CE} = 5V$
Collector-Emitter Saturation Voltage	V _{CE(sat)}		50 122	125 300	mV	$I_C = 10$ mA, $I_B = 0.5$ mA $I_C = 100$ mA, $I_B = 5.0$ mA
Base-Emitter Saturation Voltage	V _{BE(sat)}		760 880	1000 1100	mV	$I_C = 10$ mA, $I_B = 0.5$ mA $I_C = 100$ mA, $I_B = 5.0$ mA
Base-Emitter Voltage	V _{BE(on)}	580	650 725	750 800	mV	$I_C = 2.0 \text{mA}, V_{CE} = 5 \text{V}$ $I_C = 10 \text{mA}, V_{CE} = 5 \text{V}$
Current Gain-Bandwidth Product	f _T	100	170		MHz	$V_{CE} = 5V$, $I_{C} = 10$ mA, f = 100MHz
Collector-Base Capacitance	C _{cbo}		1.5		pF	V _{CB} = 10V, f = 1.0MHz

Notes: 4. Short duration pulse test used to minimize self-heating effect.



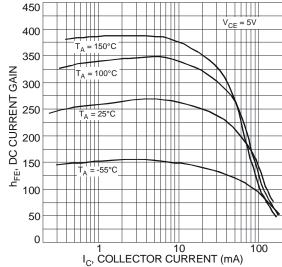
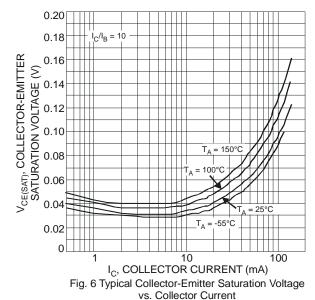
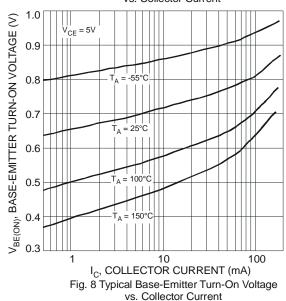
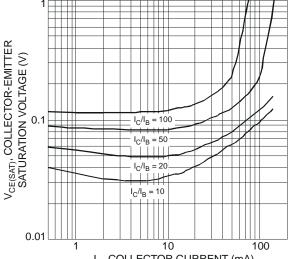


Fig. 5 Typical DC Current Gain vs. Collector Current









I_C, COLLECTOR CURRENT (mA)
Fig. 7 Typical Collector-Emitter Saturation Voltage vs. Collector Current

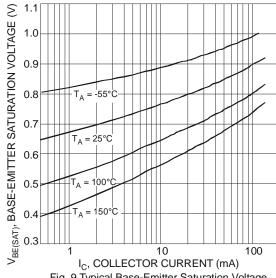
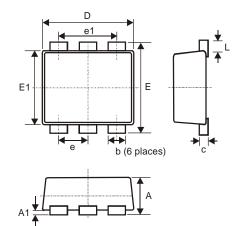


Fig. 9 Typical Base-Emitter Saturation Voltage vs. Collector Current

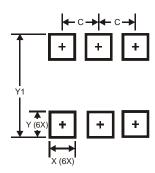
Package Outline Dimensions



	SOT-963				
Dim	Min	Max	Тур		
Α	0.40	0.50	0.45		
A1	0	0.05	-		
С	0.120	0.180	0.150		
D	0.95	1.05	1.00		
Е	0.95	1.05	1.00		
E1	0.75	0.85	0.80		
L	0.05	0.15	0.10		
b	0.10	0.20	0.15		
е	0.35 Typ				
e1	0.70 Typ				
All	All Dimensions in mm				



Suggest Pad Layout



Dimensions	Value (in mm)
С	0.350
Х	0.200
Υ	0.200
Y1	1.100

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